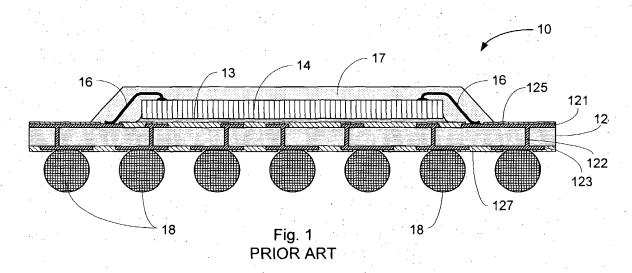
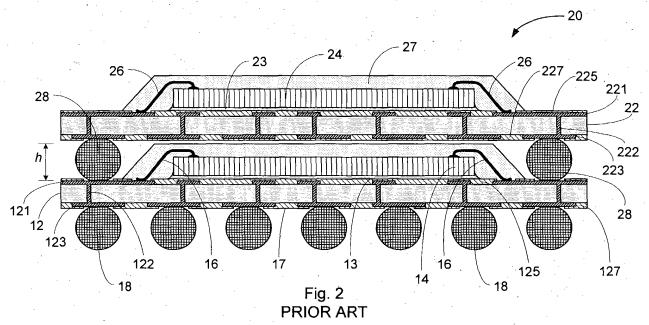
Inventor: Marcos Karnezos
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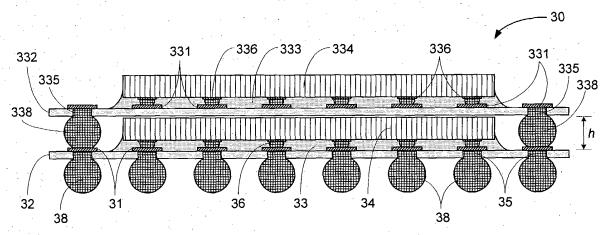


Fig. 3 PRIOR ART

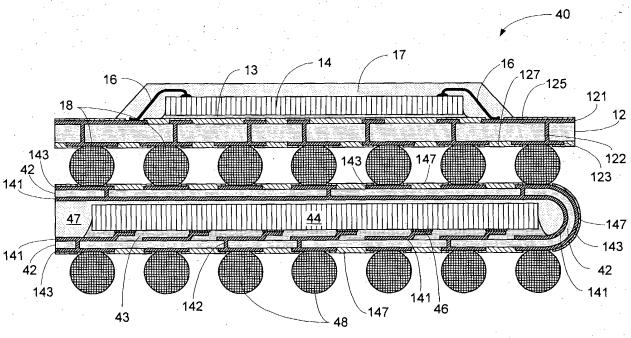
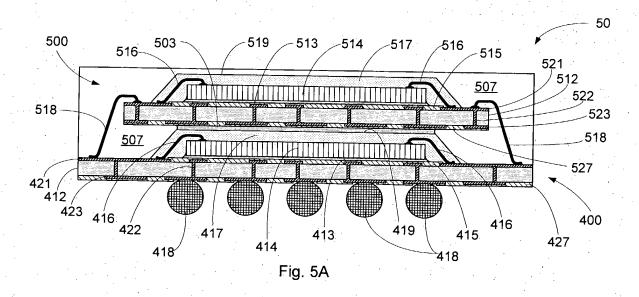
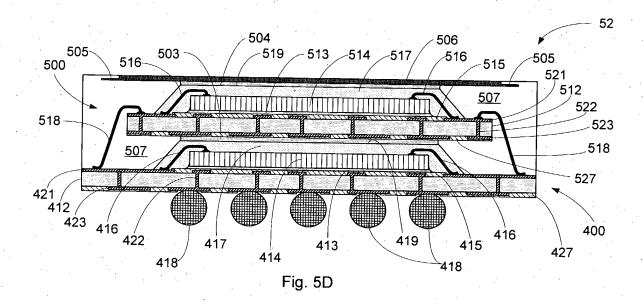
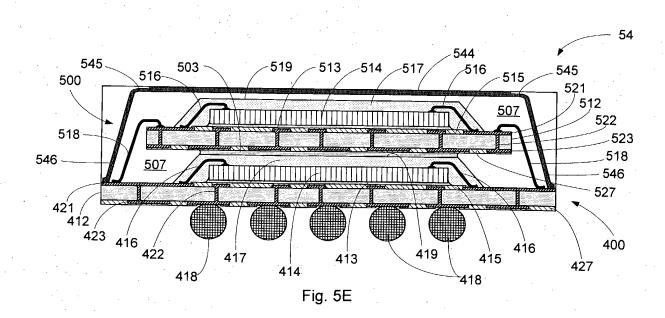


Fig. 4 PRIOR ART

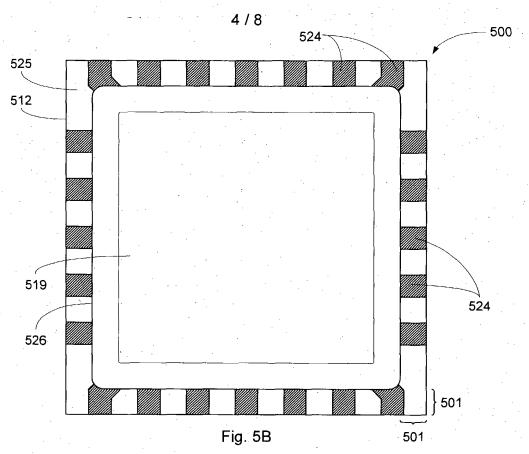
Inventor: Marcos Karnezos
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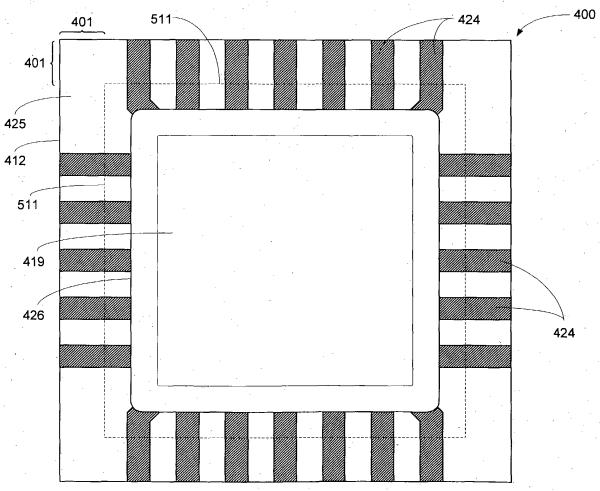
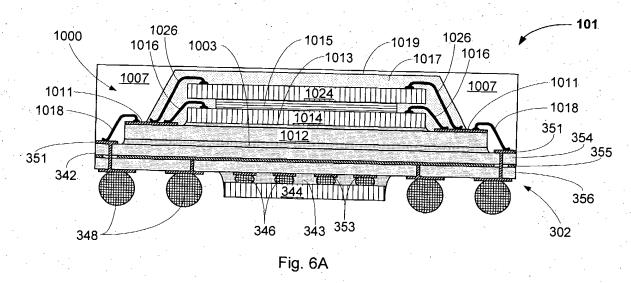
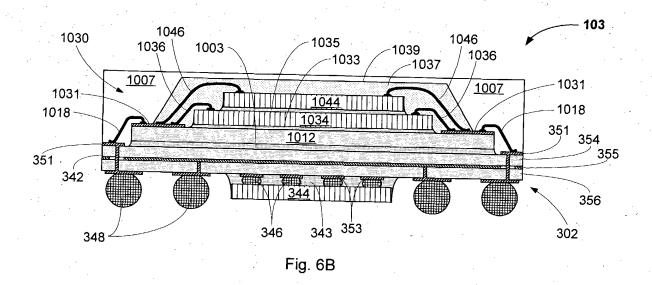
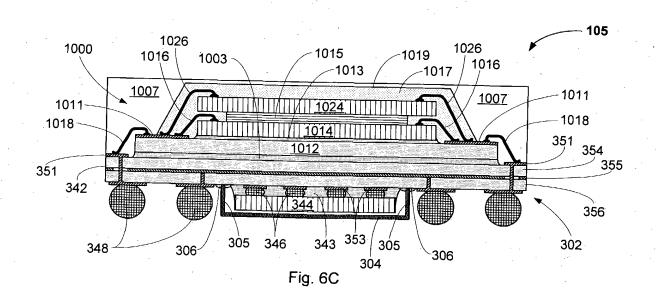


Fig. 5C

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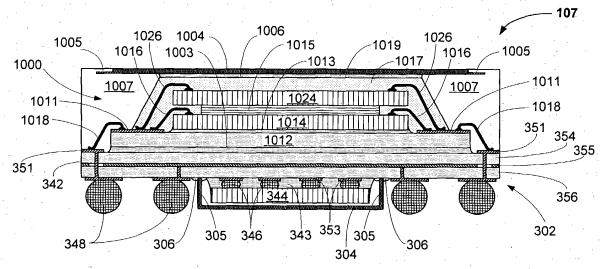


Fig. 6D

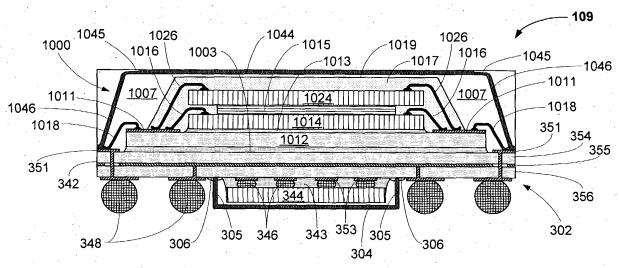
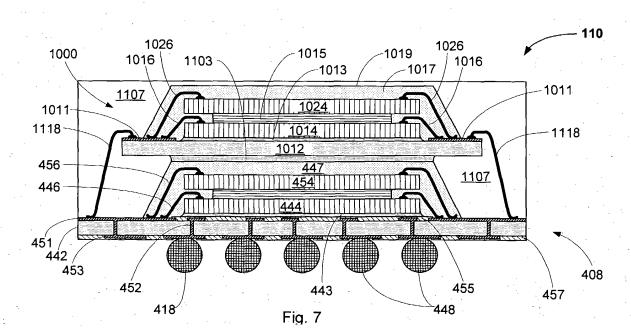


Fig. 6E



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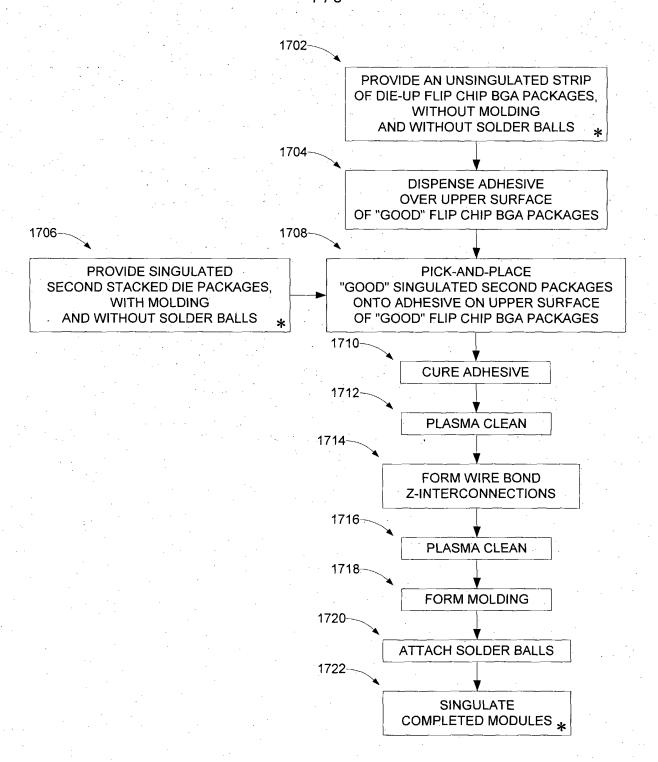


Fig. 8

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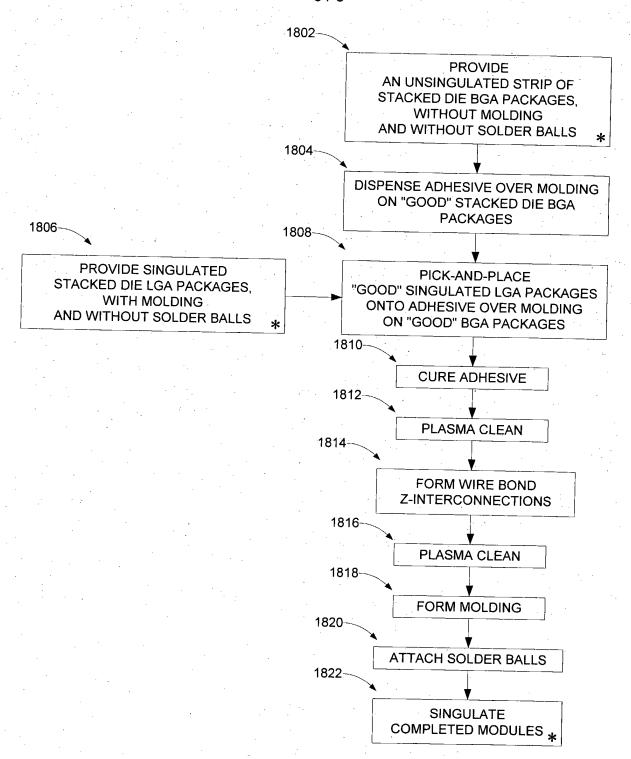


Fig. 9